



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	26-07-2017
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**


<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L152C8U6A	SOMI*429XXXY	A	998Z	26-07-2017
Amount	UoM	Unit type	ST ECOPACK Grade	
97,90	mg	Each	ECOPACK® 2	
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		


  
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Package Designator	Size	Nbr of instances	Shape	
QFN	7X7X0.55	48	No lead	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	SOMI*429XXXY				5999999.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4,057	mg	Supplier	die	Silicon (Si)	7440-21-3		3,757	mg	926054	38374
				Supplier	metallization	Aluminium (Al)	7429-90-5		0,026	mg	6409	266
				Supplier	metallization	Copper (Cu)	7440-50-8		0,087	mg	21444	889
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0,010	mg	2465	102
				Supplier	metallization	Titanium (Ti)	7440-32-6		0,013	mg	3204	133
				Supplier	metallization	Tungsten (W)	7440-33-7		0,001	mg	246	10
				Supplier	Passivation	Silicon Nitride	12033-89-5		0,023	mg	5669	235
				Supplier	Passivation	Silicon Oxide	7631-86-9		0,140	mg	34508	1430
				Supplier	Metals	Silver	7440-22-4		0,755	mg	704535	7715
				Supplier	Plastics/polymers	Bisphenol-F, epoxy resin	9003-36-5		0,052	mg	48437	530
Supplier	Polymers	Fatty acids, polymers with epichlorohydrin	68475-94-5		0,052	mg	48437	530				
Supplier	Organic Compounds	Gamma Butyrolactone	96-48-0		0,052	mg	48437	530				
Supplier	Epoxy Resin	Epoxy Resin	Proprietary		0,052	mg	48437	530				
Supplier	Amines	Poly(Oxy(methyl-1, 2-ethanediy))	9046-10-0		0,052	mg	48437	530				
Supplier	Metallic compounds	Copper Oxide	1317-38-0		0,052	mg	48437	530				
Supplier	Organic Compounds	1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8		0,005	mg	4844	53				
Mold Compound_EME-G770_Sumitor	M-011 Other inorganic materials	34,883	mg	Supplier	Epoxy Resin	Epoxy Resin A	Proprietary		0,694	mg	19837	7091
				Supplier	Epoxy Resin	Epoxy Resin B	Proprietary		0,694	mg	19837	7091
				Supplier	Phenol Resin	Phenol Resin A	Proprietary		0,694	mg	19837	7091
				Supplier	Phenol Resin	Phenol Resin B	Proprietary		0,694	mg	19837	7091
				Supplier	Glass	Silica (Amorphous) A	60676-86-0		25,520	mg	732452	-739341
				Supplier	Glass	Silica (Amorphous) B	7631-86-9		5,696	mg	162767	58181
				Supplier	Metallic compounds	Metal Hydroxide	Proprietary		0,694	mg	19837	7091
				Supplier	Additives	Carbon black	1333-86-4		0,196	mg	5595	2000
Bonding wire_WIRE AG 0.8MIL SI TYPE	Bonding Wire	0,322	mg	Supplier	Metals	Silver	7440-22-4		0,309	mg	960000	3155
				Supplier	Metals	Others	Proprietary		0,013	mg	40000	131
				Supplier	Metals	Tin	7440-31-5		3,693	mg	1000000	37717
Anode Ball_Pure Tin_Nuo Nengda	M-011 Other inorganic materials	3,693	mg	Supplier	Metals	Nickel	7440-02-0		1,582	mg	29365	16160
				Supplier	Glass	Silicon	7440-21-3		0,350	mg	6500	3577
Lead frame_C7+AG_HDS	Copper & its alloys	53,878	mg	Supplier	Metals	Magnesium	7439-95-4		0,084	mg	1565	861
				Supplier	Metals	Silver	7440-22-4		3,394	mg	63000	34670
				Supplier	Metals	Copper	7440-50-8		48,467	mg	899570	495046